Abstract Of The Disclosure

An opto-electronic package includes an enclosed package, a plurality of the electrical contacts extending into the enclosed package, an optical integrated circuit mounted within the package and coupled to the electrical contacts, and optical fibers extending through opposite ends of the package to the optical integrated circuit along a common plane. The package is comprised of a package body and an opposite package lid joined together at an interface substantially at the common plane, and configured to form end pipes around the optical fibers at the opposite ends of the package. This enables the optical fibers to be laid into feedthroughs formed by opposing portions of the package body and the package lid before they are joined together, eliminating the need to feed the fibers through opposite apertures in the package body and for a separate subassembly to mount the opposite fibers and the integrated circuit. The package body and the package lid are solder sealed to each other, and the optical fibers are solder sealed with the end pipes at the opposite ends of the package, to form a hermetically sealed package.